

MICROWAVE BONDING OF THIN FILM METAL COATED SUBSTRATES

Abstract of Disclosure

Bonding of materials such as MEMS materials is carried out using microwaves. High microwave absorbing films are placed within a microwave cavity containing other less microwave absorbing materials, and excited to cause selective heating in the skin depth of the films. This causes heating in one place more than another. This thereby minimizes unwanted heating effects during the microwave bonding process.

Figures